



Material Content Data Sheet



Sales Product Name				IPD068N10N3 G		Issued		19. July 2018	
MA#				MA001344442					
Package				PG-TO252-3-313		Weight*		320.76 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.560	1.73	1.73	17335	17335	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		459		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
wire	non noble metal	copper	7440-50-8	147.096	45.87	45.93	458579	459176	
	non noble metal	aluminium	7429-90-5	4.300	1.34	1.34	13406	13406	
encapsulation	organic material	carbon black	1333-86-4	1.350	0.42		4208		
	plastics	epoxy resin	-	23.620	7.36		73637		
leadfinish	inorganic material	silicondioxide	60676-86-0	110.002	34.29	42.07	342938	420783	
	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11660	11660	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4429	4440	
solder	noble metal	silver	7440-22-4	0.107	0.03		333		
	non noble metal	tin	7440-31-5	0.086	0.03		267		
heatspreader	non noble metal	lead	7439-92-1	4.085	1.27	1.33	12735	13335	
	non noble metal	iron	7439-89-6	0.019	0.01		60		
*deviation	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	5.98	5.99	59787	59865	
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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